Product data sheet

1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in a medium power DFN2020MD-6 (SOT1220) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Extended temperature range T_i = 175 °C
- · Side wettable flanks for optical solder inspection
- Small and leadless ultra thin SMD plastic package: 2 x 2 x 0.65 mm
- Trench MOSFET technology
- AEC-Q101 qualified

3. Applications

- Relay driver
- · High-speed line driver
- · Low-side load switch
- · Switching circuits

4. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|-------------------|----------------------------------|---|--|-----|-----|-----|------|
| V _{DS} | drain-source voltage | T _j = 25 °C | | - | - | 40 | V |
| V_{GS} | gate-source voltage | | | -15 | - | 15 | V |
| I _D | drain current | V _{GS} = 10 V; T _{sp} = 25 °C | | - | - | 19 | Α |
| P _{tot} | total power dissipation | T _{sp} = 25 °C | | - | - | 15 | W |
| Static characte | Static characteristics | | | | | | |
| R _{DSon} | drain-source on-state resistance | V_{GS} = 10 V; I_D = 8 A; T_j = 25 °C | | - | 18 | 23 | mΩ |



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5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|-----------------------|----------------|
| 1 | D | drain | 1 6 | D |
| 2 | D | drain | | |
| 3 | G | gate | 2 5 | G—(F) |
| 4 | S | source | 3 8 4 | mbb076 S |
| 5 | D | drain | Transparent top view | |
| 6 | D | drain | DFN2020MD-6 (SOT1220) | |
| 7 | D | drain | | |
| 8 | S | source | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | | | |
|-------------|-------------|---|---------|--|--|
| | Name | Description | Version | | |
| BUK9D23-40E | DFN2020MD-6 | DFN2020MD-6: plastic thermal enhanced ultra thin small outline package; no leads; 6 terminals | SOT1220 | | |

7. Marking

Table 4. Marking codes

| Type number | Marking code[1] |
|-------------|-----------------|
| BUK9D23-40E | %4B |

[1] % = placeholder for manufacturing site code

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8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|----------------------|---|---|-----|-----|------|------|
| V _{DS} | drain-source voltage | T _j = 25 °C | | - | 40 | V |
| V_{GS} | gate-source voltage | | | -15 | 15 | V |
| I _D | drain current | V _{GS} = 10 V; T _{sp} = 25 °C | | - | 19 | Α |
| | | V _{GS} = 10 V; T _{sp} = 100 °C | | - | 12 | Α |
| | | V _{GS} = 10 V; T _{amb} = 25 °C | [1] | - | 8 | Α |
| I _{DM} | peak drain current | T_{sp} = 25 °C; single pulse; $t_p \le 10 \mu s$ | | - | 76 | Α |
| P _{tot} | total power dissipation | T _{sp} = 25 °C | | - | 15 | W |
| | | T _{amb} = 25 °C | [1] | - | 2.3 | W |
| Tj | junction temperature | | | -55 | 175 | °C |
| T _{amb} | ambient temperature | | | -55 | 175 | °C |
| T _{stg} | storage temperature | | | -65 | 175 | °C |
| Source-dra | in diode | | · | | · | |
| I _S | source current | T _{sp} = 25 °C | | - | 15 | Α |
| | | T _{amb} = 25 °C | [1] | - | 2.3 | Α |
| I _{SM} | peak source current | single pulse; $t_p \le 10 \mu s$; $T_{sp} = 25 ^{\circ}C$ | | - | 62 | Α |
| ESD maxim | num rating | | | | · | , |
| V_{ESD} | electrostatic discharge voltage | НВМ | [2] | - | 500 | V |
| Avalanche | ruggedness | | | · | | |
| E _{DS(AL)S} | non-repetitive drain- source avalanche energy | $T_{j(init)}$ = 25 °C; I_D = 1.35 A; DUT in avalanche (unclamped) | | - | 28.4 | mJ |

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².

^{2]} Measured between all pins.

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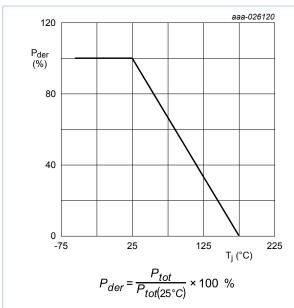


Fig. 1. Normalized total power dissipation as a function of junction temperature

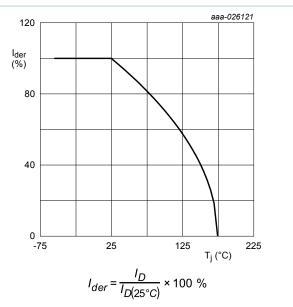


Fig. 2. Normalized continuous drain current as a function of junction temperature

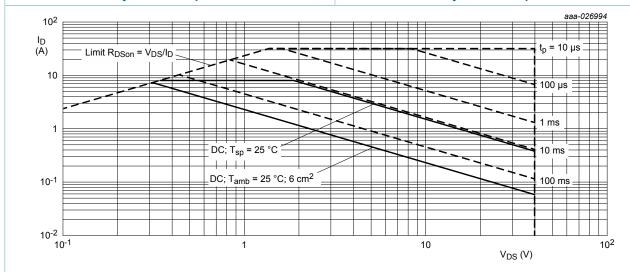


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

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9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|-----------------------|---|-------------|-----|-----|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] | - | 57 | 66 | K/W |
| R _{th(j-sp)} | thermal resistance from junction to solder point | | | - | 6 | 10 | K/W |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 6 cm².

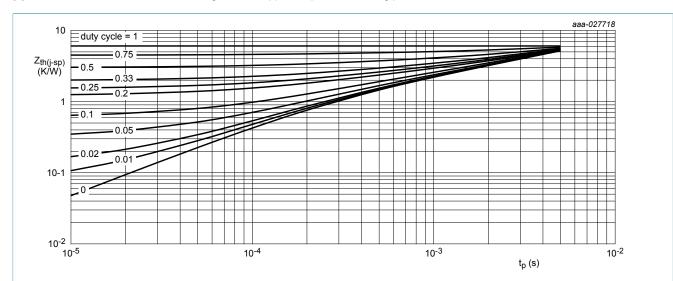


Fig. 4. Transient thermal impedance from junction to solder point as a function of pulse duration; typical values

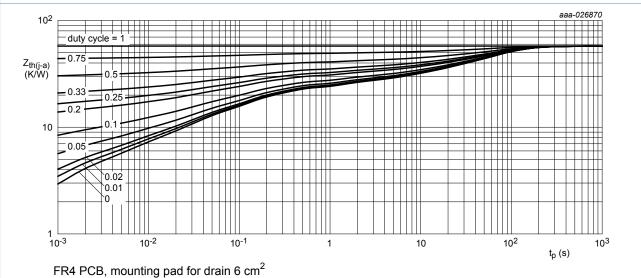


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

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10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|---------------------|-----------------------------------|--|-----|------|------|------|
| Static char | acteristics | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | I_D = 250 μ A; V_{GS} = 0 V; T_j = 25 °C | 40 | - | - | V |
| V_{GSth} | gate-source threshold voltage | $I_D = 250 \ \mu A; \ V_{DS} = V_{GS}; \ T_j = 25 \ ^{\circ}C$ | 1.4 | 1.7 | 2.1 | V |
| I _{DSS} | drain leakage current | V _{DS} = 40 V; V _{GS} = 0 V; T _j = 25 °C | - | - | 1 | μA |
| | | V _{DS} = 40 V; V _{GS} = 0 V; T _j = 175 °C | - | - | 500 | μA |
| I _{GSS} | gate leakage current | V _{GS} = 15 V; V _{DS} = 0 V; T _j = 25 °C | - | - | 100 | nA |
| | | V _{GS} = -15 V; V _{DS} = 0 V; T _j = 25 °C | - | - | -100 | nA |
| R _{DSon} | drain-source on-state | V _{GS} = 10 V; I _D = 8 A; T _j = 25 °C | - | 18 | 23 | mΩ |
| | resistance | V _{GS} = 10 V; I _D = 8 A; T _j = 175 °C | - | 33 | 43 | mΩ |
| | | V _{GS} = 4.5 V; I _D = 6.4 A; T _j = 25 °C | - | 22 | 30 | mΩ |
| 9 _{fs} | forward transconductance | $V_{DS} = 10 \text{ V}; I_D = 8 \text{ A}; T_j = 25 ^{\circ}\text{C}$ | - | 39 | - | S |
| R _G | gate resistance | f = 1 MHz | - | 1.8 | - | Ω |
| Dynamic c | haracteristics | | | | | |
| Q _{G(tot)} | total gate charge | $V_{DS} = 20 \text{ V}; I_D = 8 \text{ A}; V_{GS} = 10 \text{ V};$ | - | 11.5 | 17 | nC |
| Q _{GS} | gate-source charge | T _j = 25 °C | - | 1.7 | - | nC |
| Q_{GD} | gate-drain charge | | - | 2.1 | - | nC |
| C _{iss} | input capacitance | V _{DS} = 20 V; f = 1 MHz; V _{GS} = 0 V; | - | 637 | - | pF |
| C _{oss} | output capacitance | T _j = 25 °C | - | 102 | - | pF |
| C _{rss} | reverse transfer capacitance | | - | 52 | - | pF |
| t _{d(on)} | turn-on delay time | $V_{DS} = 20 \text{ V}; I_D = 8 \text{ A}; V_{GS} = 10 \text{ V};$ | - | 2 | - | ns |
| t _r | rise time | $R_{G(ext)} = 6 \Omega; T_j = 25 ^{\circ}C$ | - | 6 | - | ns |
| $t_{d(off)}$ | turn-off delay time | | - | 12 | - | ns |
| t _f | fall time | | - | 4 | - | ns |
| Source-dra | in diode | | | ' | | |
| V_{SD} | source-drain voltage | $I_S = 2.3 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}$ | - | 0.8 | 1.2 | V |
| t _{rr} | reverse recovery time | $I_S = 2.3 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s};$ $V_{GS} = 0 \text{ V}; V_{DS} = 20 \text{ V}; T_i = 25 ^{\circ}\text{C}$ | - | 12.9 | - | ns |
| | | | | | | |

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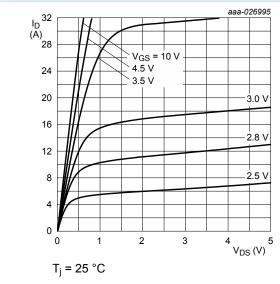


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

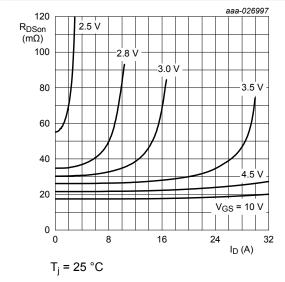


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

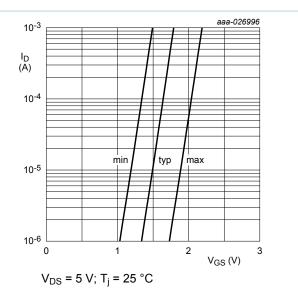


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

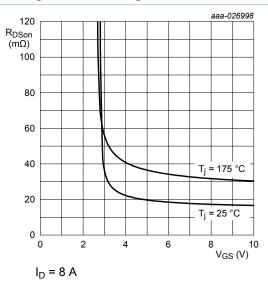


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

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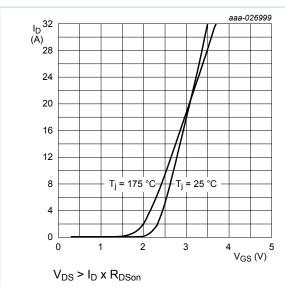


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

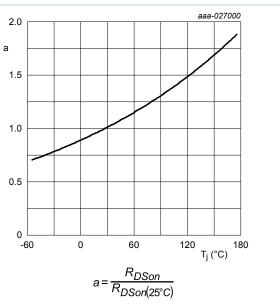


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

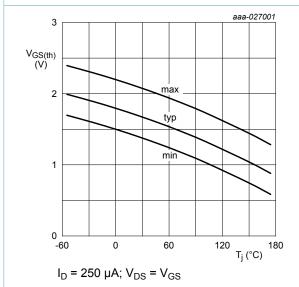


Fig. 12. Gate-source threshold voltage as a function of junction temperature

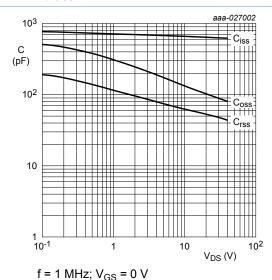


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

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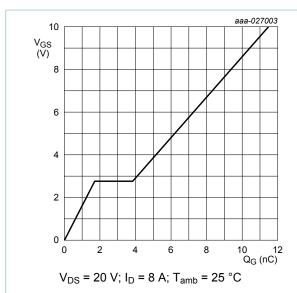


Fig. 14. Gate-source voltage as a function of gate charge; typical values

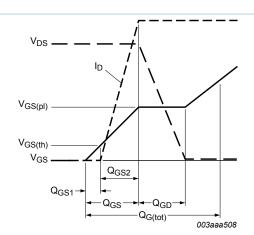


Fig. 15. Gate charge waveform definitions

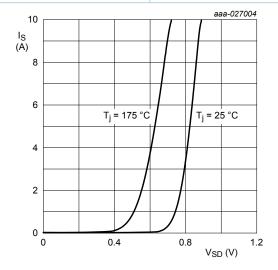
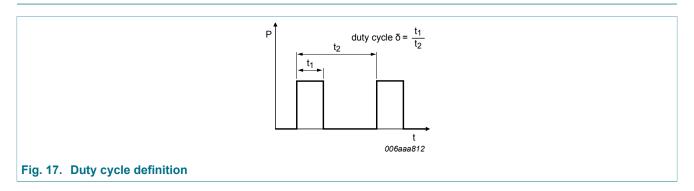


Fig. 16. Source current as a function of source-drain voltage; typical values

 $V_{GS} = 0 V$

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11. Test information

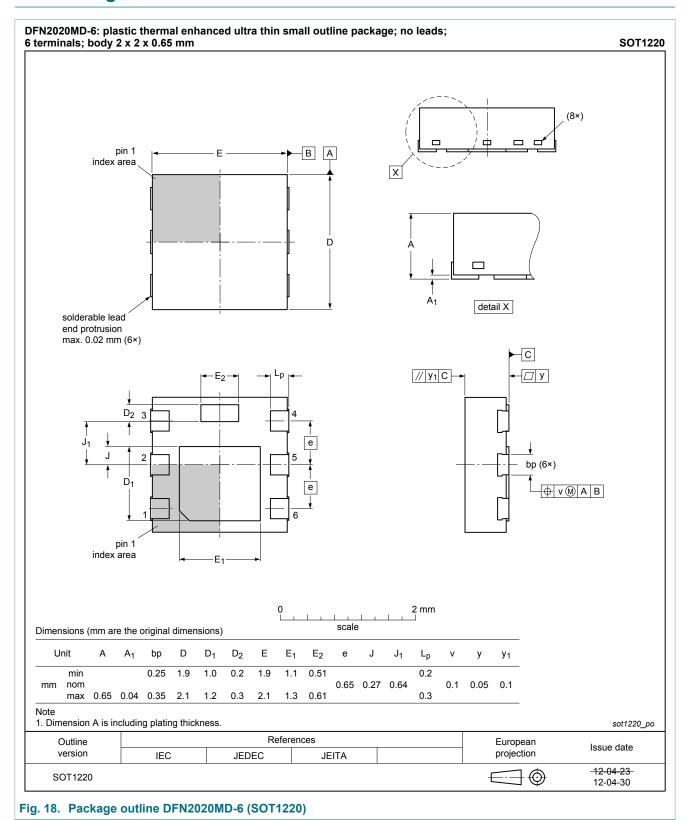


Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

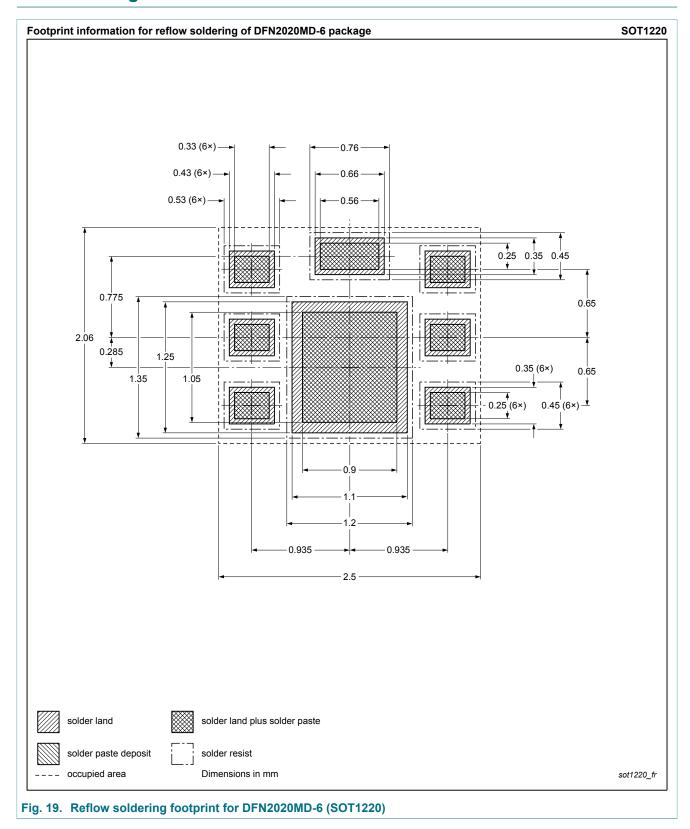
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12. Package outline



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13. Soldering



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14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes |
|-----------------|--------------|--------------------|---------------|------------|
| BUK9D23-40E v.1 | 20171213 | Product data sheet | - | - |

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15. Legal information

Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

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